

ESI 5335

LASER DRILL

December 2018

Netvia Group is pleased to announce we have completed installation and training on our ESI 5335 laser system for PCB manufacturing. The ESI 5335 delivers industry leading capabilities for UV laser via drilling / cutting and is optimized for processing both flex and rigid-flex PCB's. The laser system also addresses other high accuracy applications such as routing, patterning, and skiving which is achieved through a combination of a compound beam and solid state optical technology. The ESI 5335 optimizes Netvia Group's processing and production capabilities, which puts our customers in a position to keep up with the increasing demands of the electronics industry.

With this addition to our printed circuit board fabrication, Netvia Group continues to prove its commitment to continuous improvement in quality and process. This is just the latest example of how Netvia Group continues to invest profits for the future and in order to provide the market-leading technological capability and rapid turn around time that our customers demand.

To learn more about what Netvia Group can do for your business, sales@netviagroup.com or call 972-573-1400 to immediately talk to a real person and receive a prompt and accurate PCB fabrication quote. We look forward to working with you!

Key Features

- Nanosecond 11 watt UV
- Precision Pulse diode
- Flex PCB Laser Processing
- Rigid-Flex Laser Processing
- Laser micromachining
- Blind via drilling (rigid / flex)
- Through via drilling (flex)
- Routing (rigid / flex)
- Patterning (rigid / flex)
- Skiving (rigid / flex)
- Coverlay routing (flex)
- Soldermask ablation (rigid)

